

## **MM54HC251/MM74HC251 8-Channel TRI-STATE® Multiplexer**

### **General Description**

This 8-channel digital multiplexer with TRI-STATE outputs utilizes advanced silicon-gate CMOS technology. Along with the high noise immunity and low power consumption of standard CMOS integrated circuits, it possesses the ability to drive 10 LS-TTL loads. The large output drive capability and TRI-STATE feature make this part ideally suited for interfacing with bus lines in a bus oriented system.

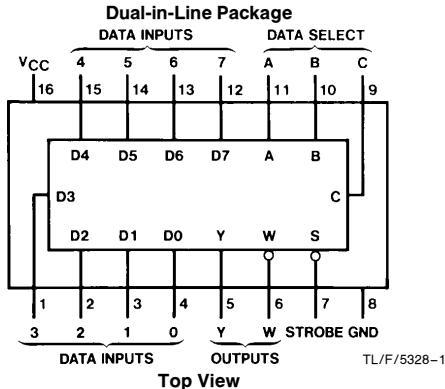
This multiplexer features both true (Y) and complement (W) outputs as well as a STROBE input. The STROBE must be at a low logic level to enable this device. When the STROBE input is high, both outputs are in the high impedance state. When enabled, address information on the data select inputs determines which data input is routed to the Y and W

outputs. The 54HC/74HC logic family is speed, function, as well as pinout compatible with the standard 54LS/74LS logic family. All inputs are protected from damage due to static discharge by internal diode clamps to  $V_{CC}$  and ground.

### **Features**

- Typical propagation delay  
Data select to Y: 26 ns
- Wide supply range: 2–6V
- Low power supply quiescent current: 80  $\mu$ A maximum (74HC)
- TRI-STATE outputs for interface to bus oriented systems

### **Connection and Logic Diagrams**



### **Truth Table**

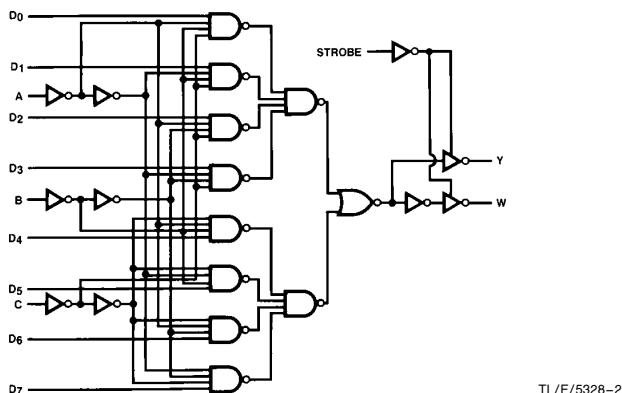
Inputs			Outputs	
Select		Strobe S	Y	W
C	B	A		
X	X	X	H	Z Z
L	L	L	L	D0 D0
L	L	H	L	D1 D1
L	H	L	L	D2 D2
L	H	H	L	D3 D3
H	L	L	L	D4 D4
H	L	H	L	D5 D5
H	H	L	L	D6 D6
H	H	H	L	D7 D7

H = high logic level, L = logic level

X = irrelevant, Z = high impedance (off)

D0, D1 . . . D7 = the level of the respective D input

Order Number MM54HC251 or MM74HC251



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## Absolute Maximum Ratings (Notes 1 & 2)

If Military/Aerospace specified devices are required, please contact the National Semiconductor Sales Office/Distributors for availability and specifications.

Supply Voltage ( $V_{CC}$ )	−0.5 to +7.0V
DC Input Voltage ( $V_{IN}$ )	−1.5 to $V_{CC}$ + 1.5V
DC Output Voltage ( $V_{OUT}$ )	−0.5 to $V_{CC}$ + 0.5V
Clamp Diode Current ( $I_{IK}, I_{OK}$ )	±20 mA
DC Output Current, per pin ( $I_{OUT}$ )	±25 mA
DC $V_{CC}$ or GND Current, per pin ( $I_{CC}$ )	±50 mA
Storage Temperature Range ( $T_{STG}$ )	−65°C to +150°C
Power Dissipation ( $P_D$ ) (Note 3)	600 mW
S.O. Package only	500 mW
Lead Temp. ( $T_L$ ) (Soldering 10 seconds)	260°C

## Operating Conditions

	Min	Max	Units
Supply Voltage ( $V_{CC}$ )	2	6	V
DC Input or Output Voltage ( $V_{IN}, V_{OUT}$ )	0	$V_{CC}$	V
Operating Temp. Range ( $T_A$ ) MM74HC	−40	+85	°C
MM54HC	−55	+125	°C
Input Rise or Fall Times ( $t_r, t_f$ )	$V_{CC} = 2.0V$ $V_{CC} = 4.5V$ $V_{CC} = 6.0V$	1000 500 400	ns

## DC Electrical Characteristics (Note 4)

Symbol	Parameter	Conditions	$V_{CC}$	$T_A = 25^\circ C$		$74HC$	$54HC$	Units
				Typ	Guaranteed Limits			
$V_{IH}$	Minimum High Level Input Voltage		2.0V 4.5V 6.0V		1.5 3.15 4.2	1.5 3.15 4.2	1.5 3.15 4.2	V
$V_{IL}$	Maximum Low Level Input Voltage**		2.0V 4.5V 6.0V		0.5 1.35 1.8	0.5 1.35 1.8	0.5 1.35 1.8	V
$V_{OH}$	Minimum High Level Output Voltage	$V_{IN} = V_{IH}$ or $V_{IL}$ $ I_{OUT}  \leq 20 \mu A$	2.0V 4.5V 6.0V	2.0 4.5 6.0	1.9 4.4 5.9	1.9 4.4 5.9	1.9 4.4 5.9	V
		$V_{IN} = V_{IH}$ or $V_{IL}$ $ I_{OUT}  \leq 4.0 \text{ mA}$ $ I_{OUT}  \leq 5.2 \text{ mA}$	4.5V 6.0V	4.2 5.7	3.98 5.48	3.84 5.34	3.7 5.2	V
$V_{OL}$	Maximum Low Level Output Voltage	$V_{IN} = V_{IH}$ or $V_{IL}$ $ I_{OUT}  \leq 20 \mu A$	2.0V 4.5V 6.0V	0 0 0	0.1 0.1 0.1	0.1 0.1 0.1	0.1 0.1 0.1	V
		$V_{IN} = V_{IH}$ or $V_{IL}$ $ I_{OUT}  \leq 4.0 \text{ mA}$ $ I_{OUT}  \leq 5.2 \text{ mA}$	4.5V 6.0V	0.2 0.2	0.26 0.26	0.33 0.33	0.4 0.4	V
$I_{IN}$	Maximum Input Current	$V_{IN} = V_{CC}$ or GND	6.0V		±0.1	±1.0	±1.0	μA
$I_{OZ}$	Maximum TRI-STATE Leakage Current	Strobe = $V_{CC}$ $V_{OUT} = V_{CC}$ or GND	6.0V		±0.5	±5	±10	μA
$I_{CC}$	Maximum Quiescent Supply Current	$V_{IN} = V_{CC}$ or GND $I_{OUT} = 0 \mu A$	6.0V		8.0	80	160	μA

Note 1: Absolute Maximum Ratings are those values beyond which damage to the device may occur.

Note 2: Unless otherwise specified all voltages are referenced to ground.

Note 3: Power Dissipation temperature derating — plastic "N" package: −12 mW/°C from 65°C to 85°C; ceramic "J" package: −12 mW/°C from 100°C to 125°C.

Note 4: For a power supply of  $5V \pm 10\%$  the worst case output voltages ( $V_{OH}$  and  $V_{OL}$ ) occur for HC at 4.5V. Thus the 4.5V values should be used when designing with this supply. Worst case  $V_{IH}$  and  $V_{IL}$  occur at  $V_{CC} = 5.5V$  and 4.5V respectively. (The  $V_{IH}$  value at 5.5V is 3.85V.) The worst case leakage current ( $I_{IN}$ ,  $I_{CC}$ , and  $I_{OZ}$ ) occur for CMOS at the higher voltage and so the 6.0V values should be used.

\*\* $V_{IL}$  limits are currently tested at 20% of  $V_{CC}$ . The above  $V_{IL}$  specification (30% of  $V_{CC}$ ) will be implemented no later than Q1, CY'89.

### AC Electrical Characteristics $V_{CC} = 5V$ , $T_A = 25^\circ C$ , $C_L = 15 pF$ , $t_r = t_f = 6 ns$

Symbol	Parameter	Conditions	Typ	Guaranteed Limit	Units
$t_{PHL}, t_{PLH}$	Maximum Propagation Delay A, B or C to Y		26	35	ns
$t_{PHL}, t_{PLH}$	Maximum Propagation Delay, A, B or C to W		27	35	ns
$t_{PHL}, t_{PLH}$	Maximum Propagation Delay, Any D to Y		22	29	ns
$t_{PHL}, t_{PLH}$	Maximum Propagation Delay, Any D to W		24	32	ns
$t_{PZH}, t_{PZL}$	Maximum Output Enable Time, W Output	$R_L = 1 k\Omega$ $C_L = 50 pF$	19	27	ns
$t_{PZH}, t_{PZL}$	Maximum Output Enable Time, Y Output	$R_L = 1 k\Omega$ $C_L = 50 pF$	19	26	ns
$t_{PHZ}, t_{PLZ}$	Maximum Output Disable Time W Output	$R_L = 1 k\Omega$ $C_L = 5 pF$	26	40	ns
$t_{PHZ}, t_{PLZ}$	Maximum Output Disable Time Y Output	$R_L = 1 k\Omega$ $C_L = 5 pF$	27	35	ns

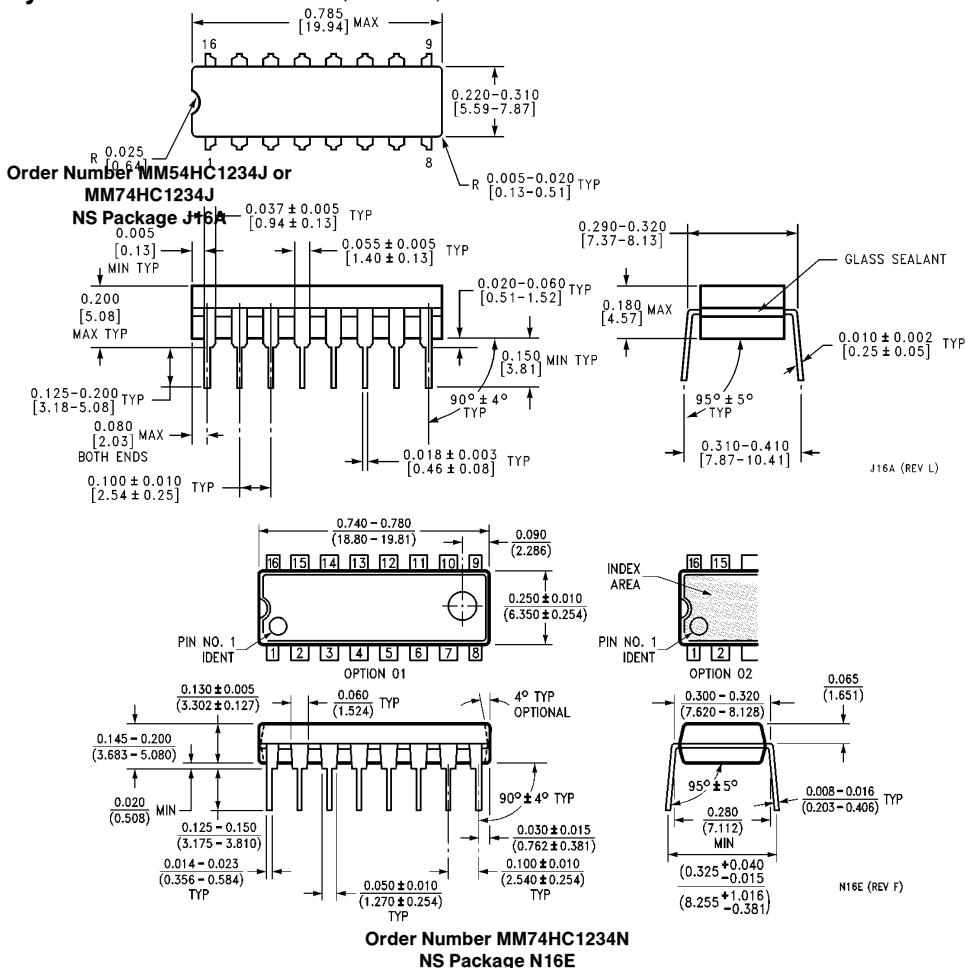
### AC Electrical Characteristics $C_L = 50 pF$ , $t_r = t_f = 6 ns$ (unless otherwise specified)

Symbol	Parameter	Conditions	$V_{CC}$	$T_A = 25^\circ C$		$74HC$	$54HC$	Units
				Typ		$T_A = -40 \text{ to } 85^\circ C$	$T_A = -55 \text{ to } 125^\circ C$	
$t_{PHL}, t_{PLH}$	Maximum Propagation Delay A, B or C to Y		2.0V 4.5V 6.0V	90 31 26	205 41 35	256 51 44	300 60 51	ns ns ns
$t_{PHL}, t_{PLH}$	Maximum Propagation Delay, A, B or C to W		2.0V 4.5V 6.0V	95 32 27	205 41 35	256 51 44	300 60 51	ns ns ns
$t_{PHL}, t_{PLH}$	Maximum Propagation Delay, any D to Y		2.0V 4.5V 6.0V	70 27 23	195 39 33	244 49 41	283 57 48	ns ns ns
$t_{PHL}, t_{PLH}$	Maximum Propagation Delay, any D to W		2.0V 4.5V 6.0V	75 29 25	185 37 32	231 46 40	268 54 46	ns ns ns
$t_{PZH}, t_{PZL}$	Maximum Output Enable Time W Output	$R_L = 1 k\Omega$	2.0V 4.5V 6.0V	45 21 18	150 30 26	188 38 33	218 44 38	ns ns ns
$t_{PZH}, t_{PZL}$	Maximum Output Enable Time Y Output	$R_L = 1 k\Omega$	2.0V 4.5V 6.0V	45 21 18	145 29 25	181 36 31	210 42 36	ns ns ns
$t_{PHZ}, t_{PLZ}$	Maximum Output Disable Time W Output	$R_L = 1 k\Omega$	2.0V 4.5V 6.0V	60 29 25	220 44 37	275 55 46	319 64 54	ns ns ns
$t_{PHZ}, t_{PLZ}$	Maximum Output Disable Time Y Output	$R_L = 1 k\Omega$	2.0V 4.5V 6.0V	60 30 26	195 39 33	244 49 41	283 57 48	ns ns ns
$t_{THL}, t_{TLH}$	Maximum Output Rise and Fall Time		2.0V 4.5V 6.0V	30 8 7	75 15 13	95 19 16	110 22 19	ns ns ns
$C_{PD}$	Power Dissipation Capacitance (Note 5)	(per package)		110				pF
$C_{IN}$	Maximum Input Capacitance			5	10	10	10	pF

Note 5:  $C_{PD}$  determines the no load dynamic power consumption,  $P_D = C_{PD} V_{CC}^2 f + I_{CC} V_{CC}$ , and the no load dynamic current consumption,  $I_S = C_{PD} V_{CC} f + I_{CC}$ .

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## Physical Dimensions inches (millimeters)



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